



**BE  MART**

**Together for Active and Efficient Buildings**



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No 818009.



# **Multifunctional EPoGs - Module reliability & manufacturing process**

- 1. Tool for simulating in-module temperature profile during lamination for different module designs**
- 2. Develop a low temperature processable encapsulant**
- 3. Extended reliability testing on material level and mini-module level**





# EPOGs size

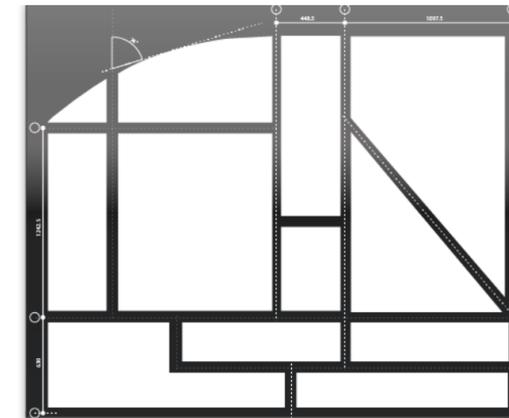
- Size depends on the on the building architectural requirements (A. Clua Longas, Proceedings of PLEA)



**Module size 600x2700mm**  
 Student Housing in Aarhus  
 (photo Lars Kvist)



**Module size 3000x4000mm**  
 Energy Cube in Konstanz  
 (photo ertex solar)



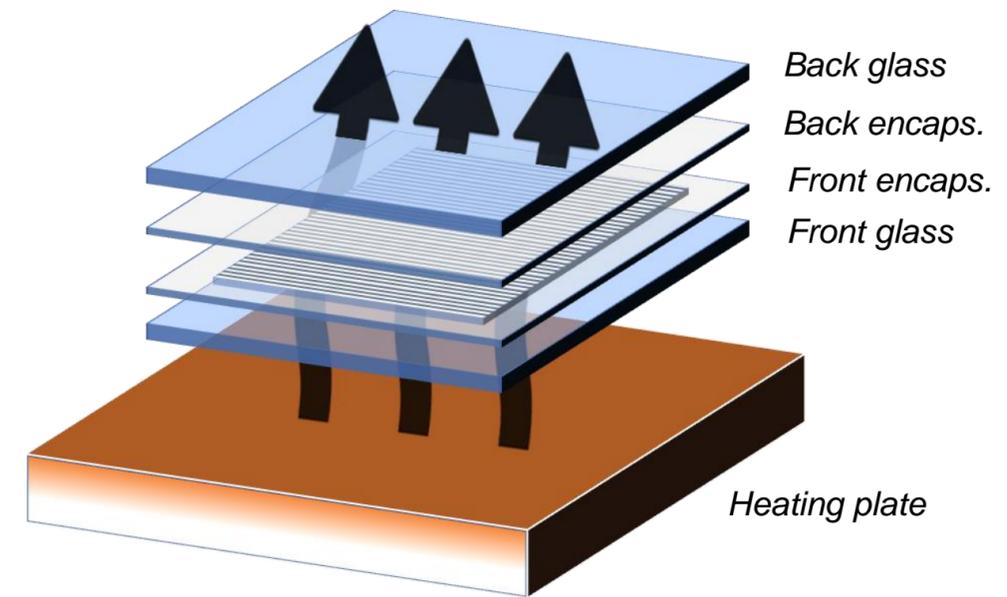
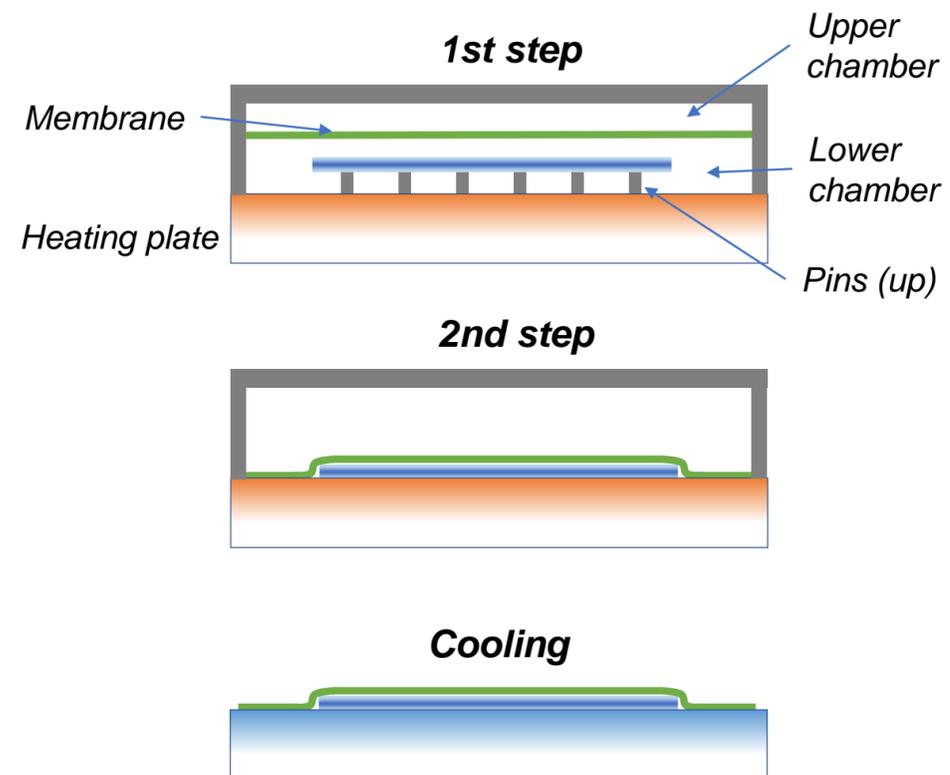
To respect the geometry of the building or to go around obstacles, "active" **cut parts** of the product are available

- Glass thickness 2.0-10.0mm to meet the mechanical and safety building requirements.





# Lamination process

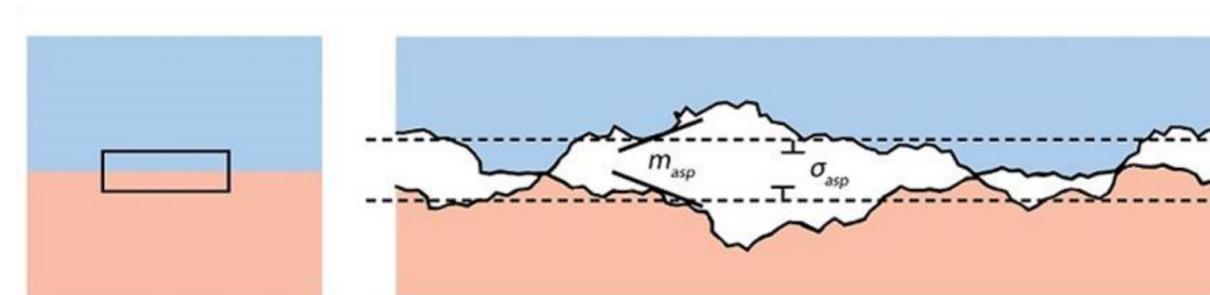
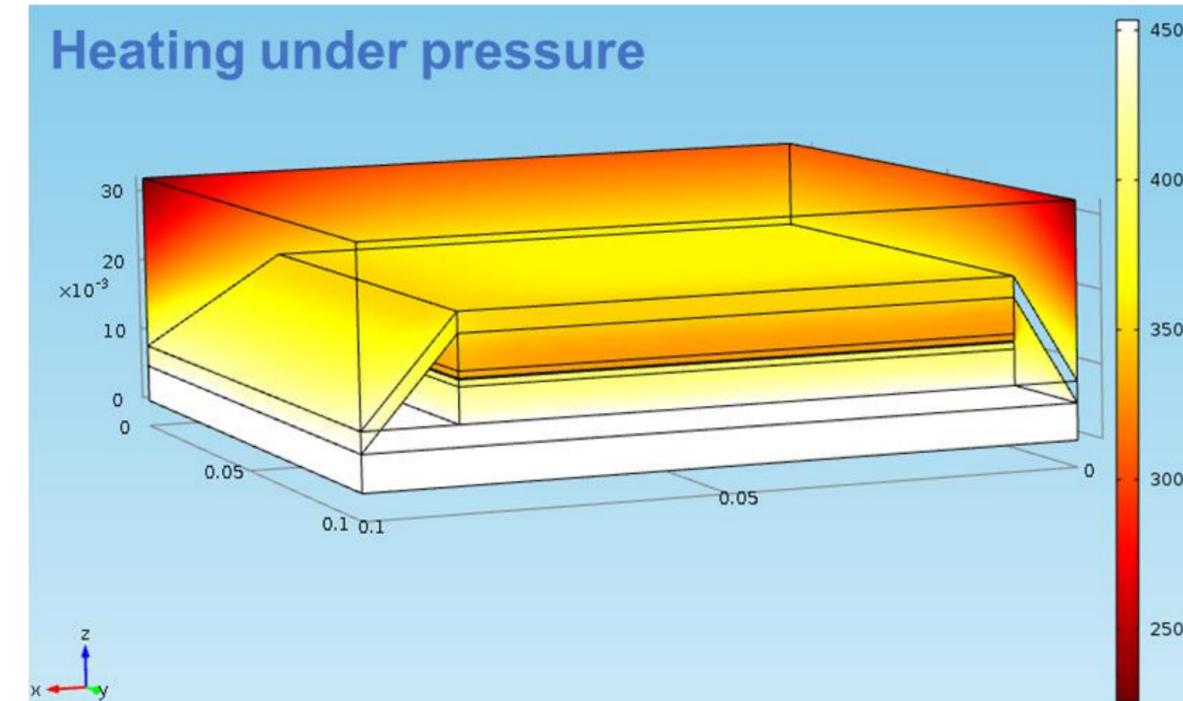
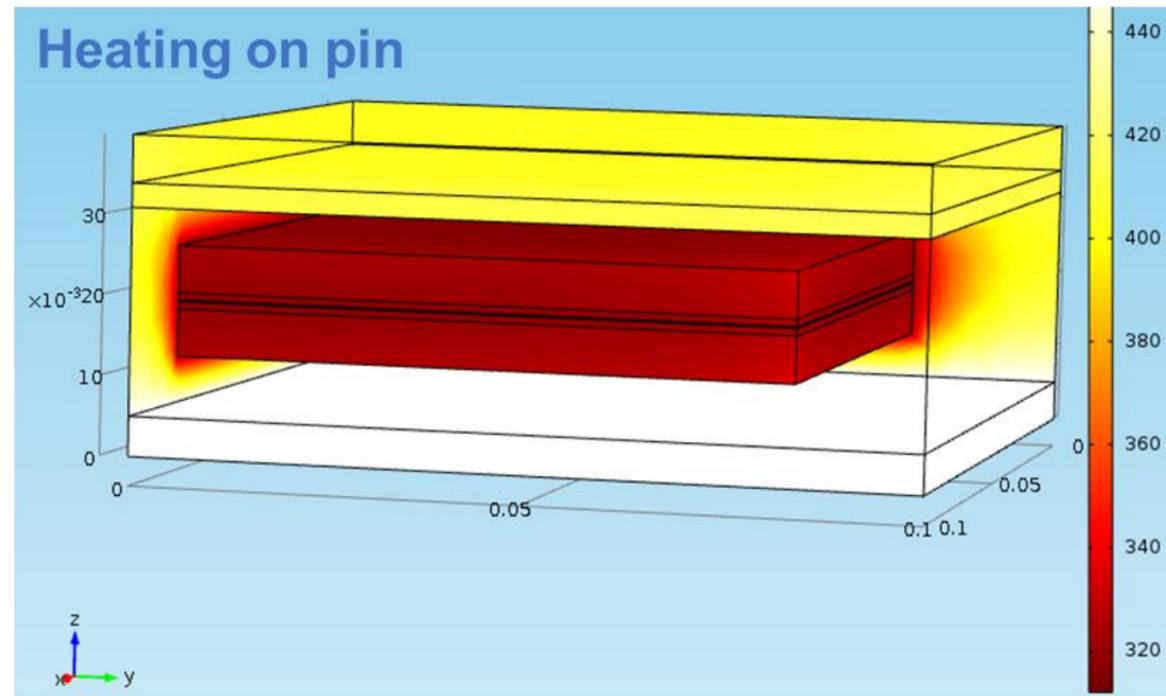


With thicker glass, longer lamination time is needed to transfer heat to the encapsulant





# Finite Element Method (FEM)



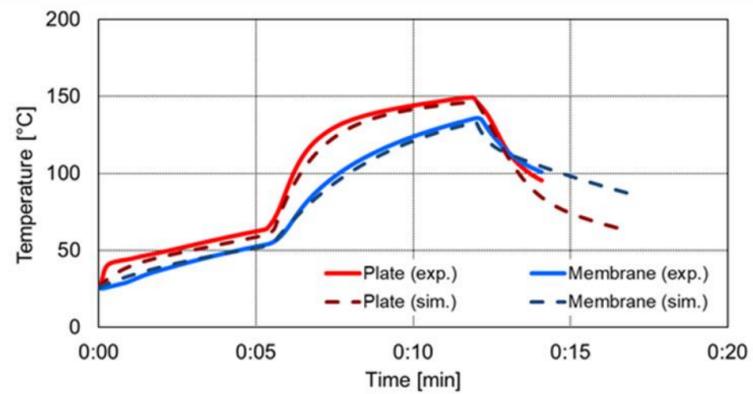
**Thermal resistance contact**





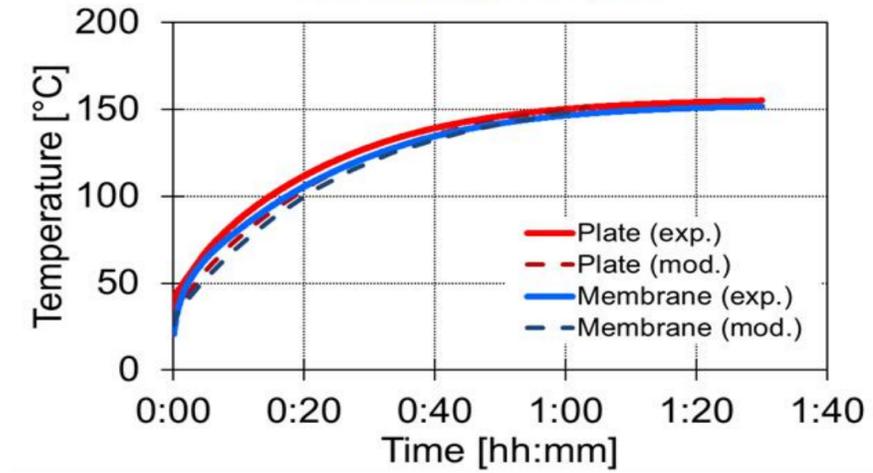
# Model validation

Complete lamination recipe sequence

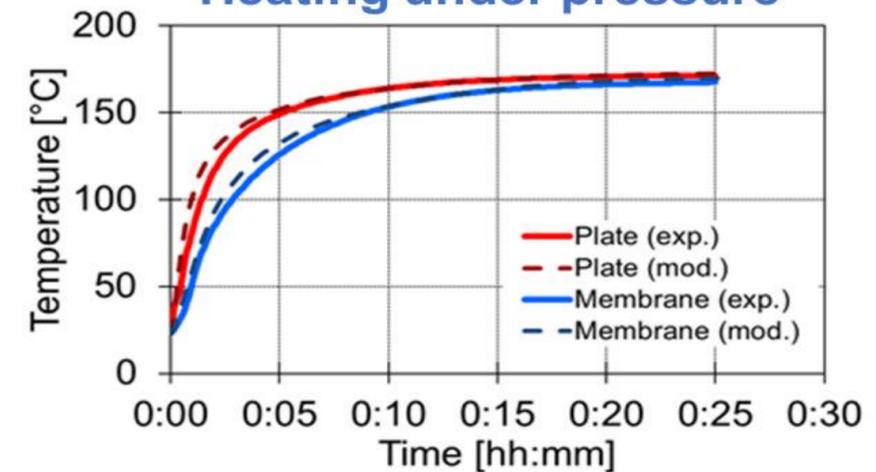


Temperature difference between experimental and simulated data at the end of the pressure step before starting the cooling is less than 2°C

Heating on pin

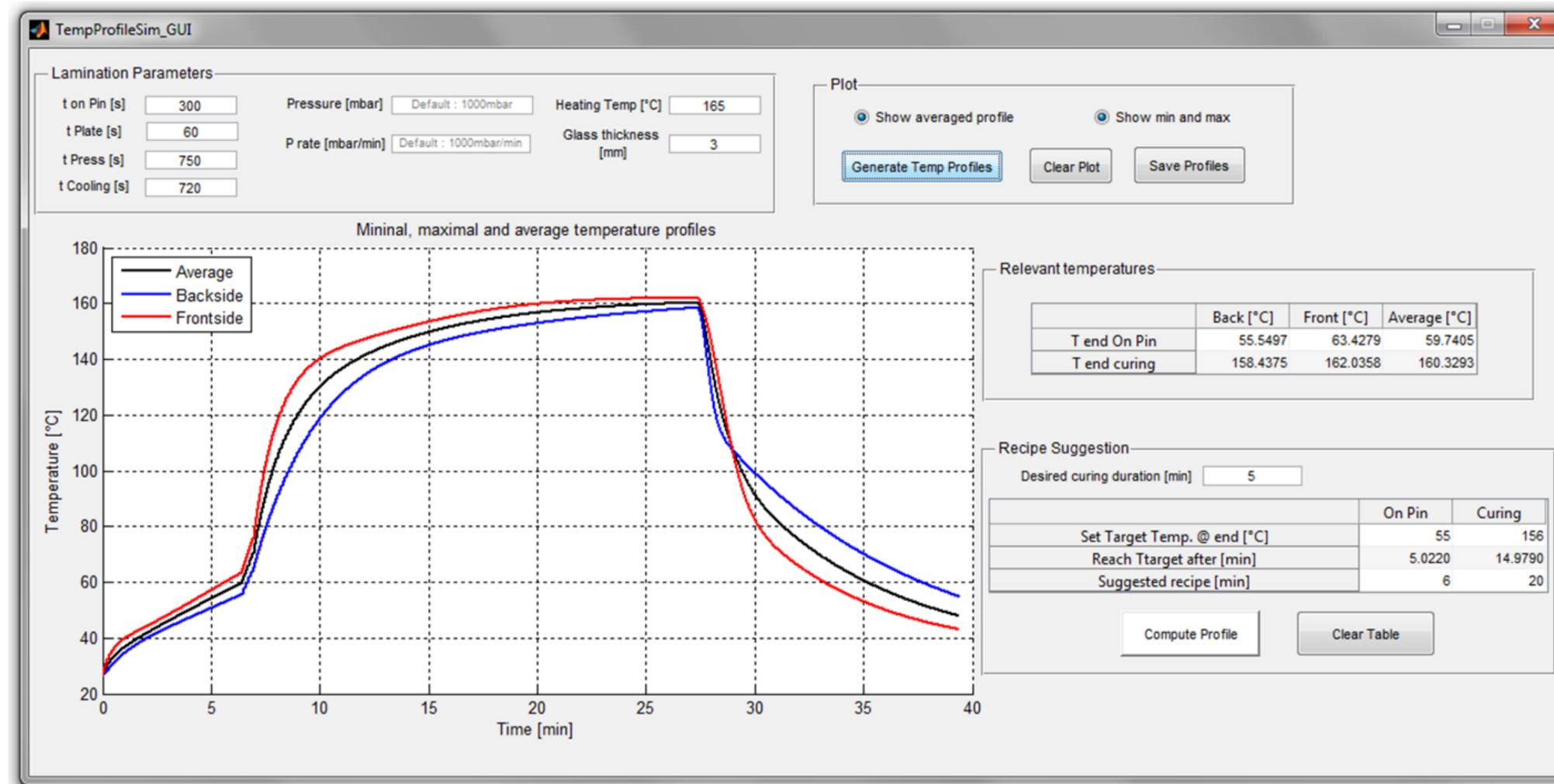


Heating under pressure





# Simulation program



GUI of the simulation program

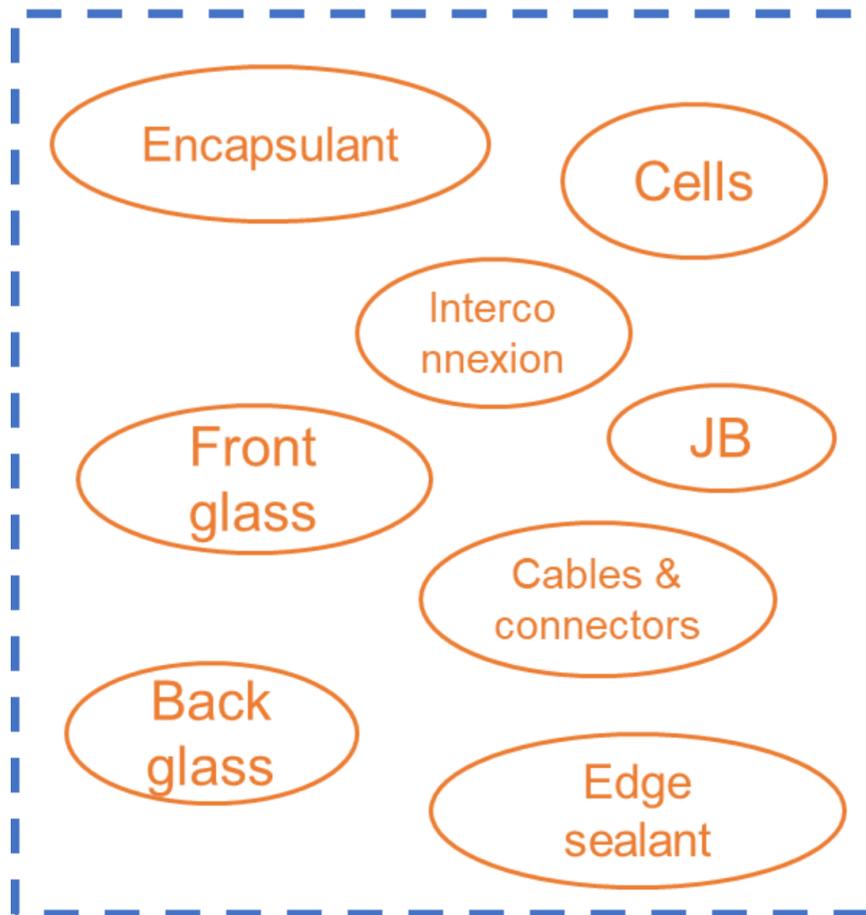






# Extended reliability testing

## PV module



### IEC 62788

Measurement procedures for materials used in photovoltaic modules

### IEC 61215

Terrestrial photovoltaic (PV) modules – Design qualification and type approval



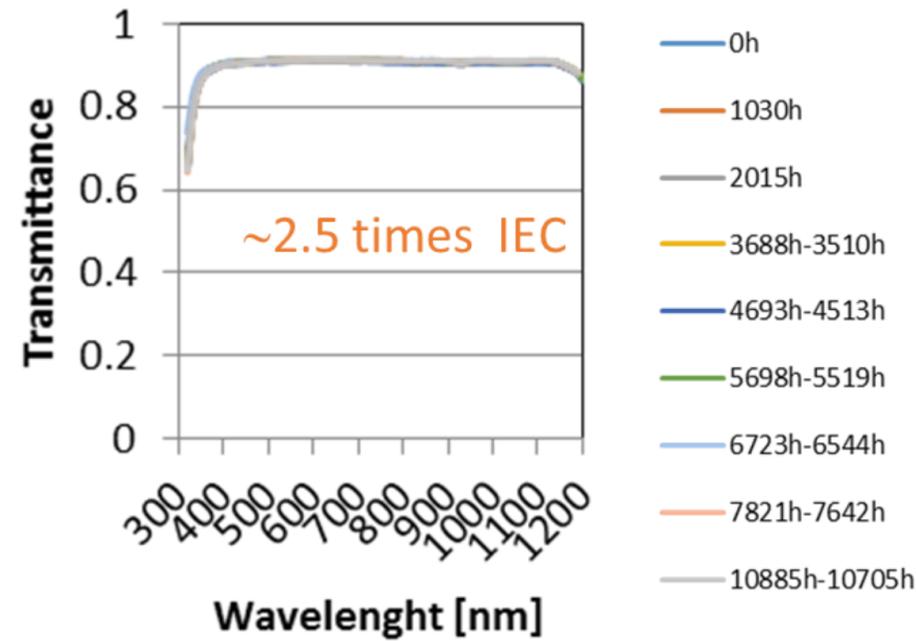


# Extended reliability testing

- Clear low temperature encapsulant

### IEC UV test

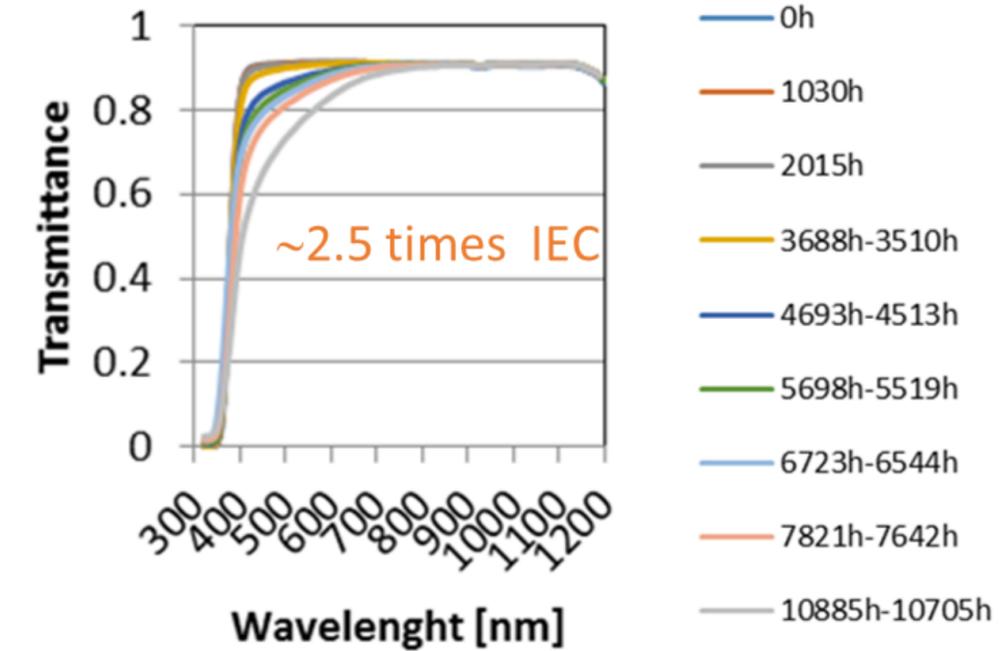
- Temp. 70°C
- Irr. 0.8 W/m<sup>2</sup> @ 340 nm
- Time: 4000h



### IEC DH test

- Temp 85°C
- Humidity: 85%
- Time: 1000h

DH Time [h]	$\Delta P_{max}$ [%]	$\Delta I_{sc}$ [%]	$\Delta FF$ [%]	$\Delta v_{oc}$ [%]
0	-	-	-	-
2318	-3.4	-0.40	-2.69	-0.23
7155	-10.1	-0.79	-8.94	-0.33
8855	-20.5	-2.61	-15.60	-3.23



DH Time [h]	$\Delta P_{max}$ [%]	$\Delta I_{sc}$ [%]	$\Delta FF$ [%]	$\Delta v_{oc}$ [%]
0	-	-	-	-
2318	-0.7	-0.62	+0.14	-0.20
7155	-0.5	-1.09	+1.54	-0.97
8855	+0.9	-1.08	+2.66	-0.56



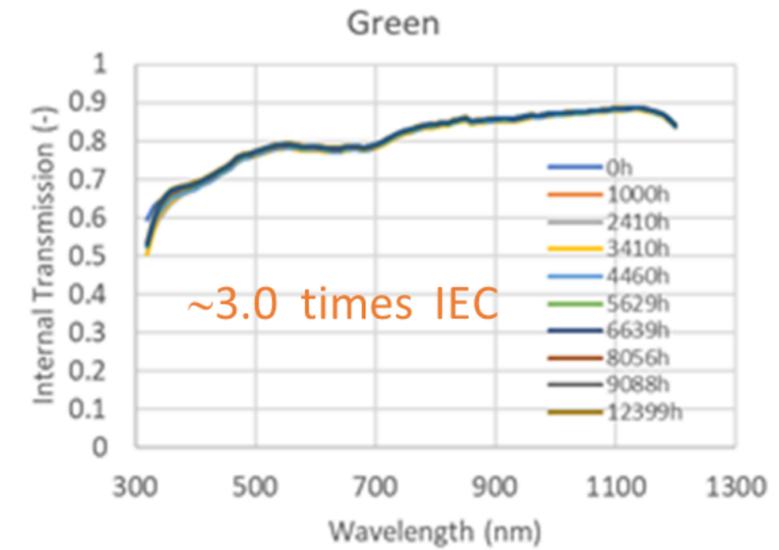
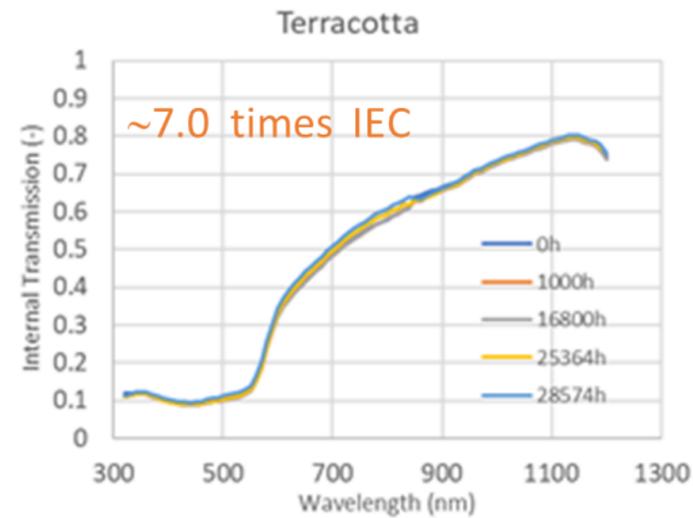
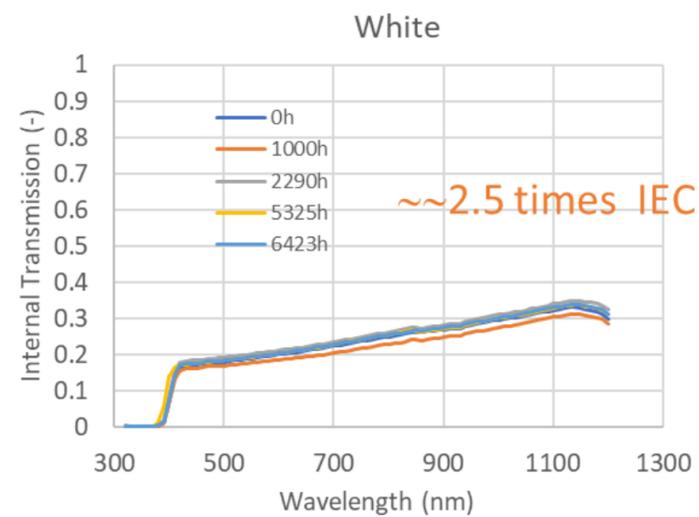


# Extended reliability testing

- Colored low temperature encapsulant

### IEC UV test

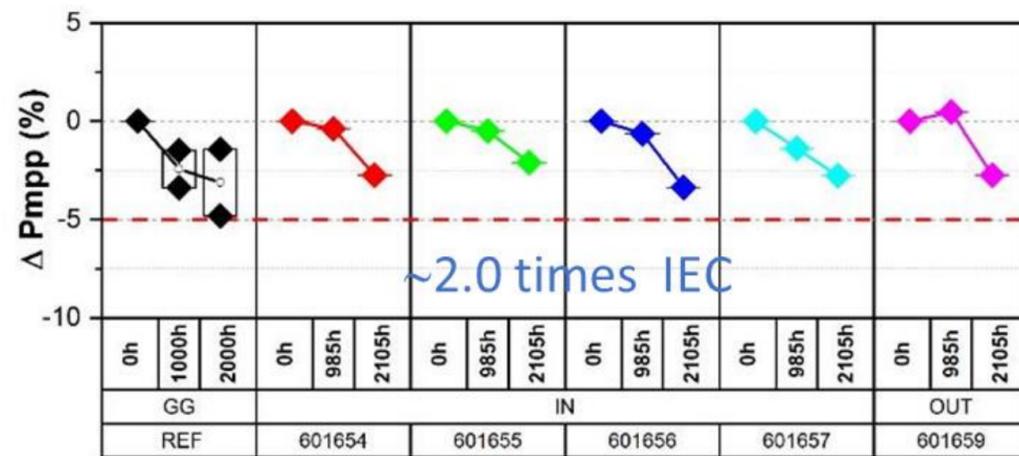
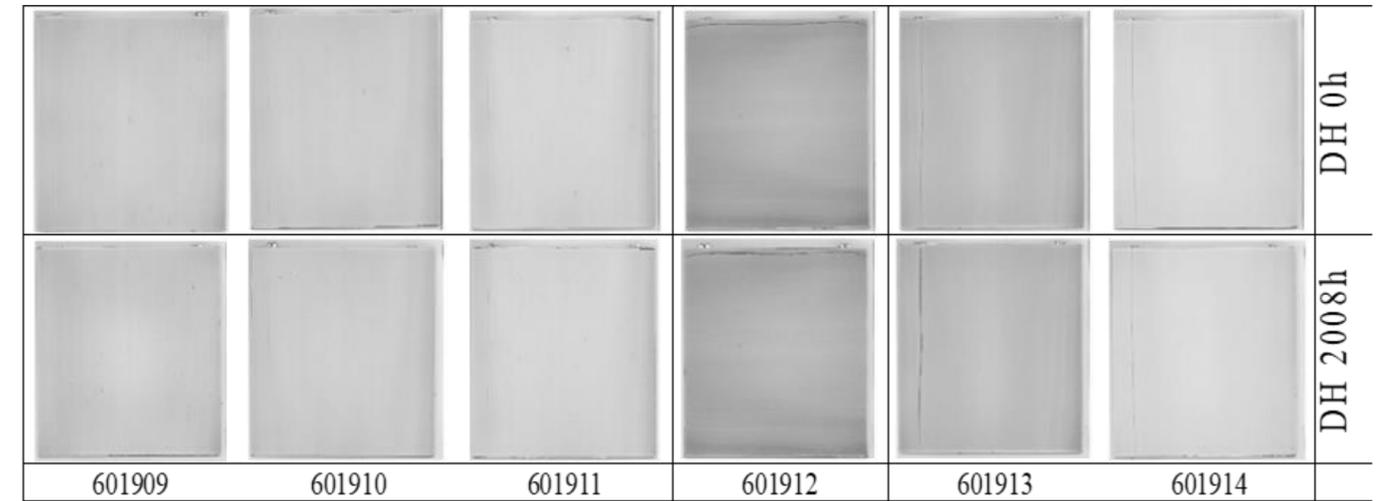
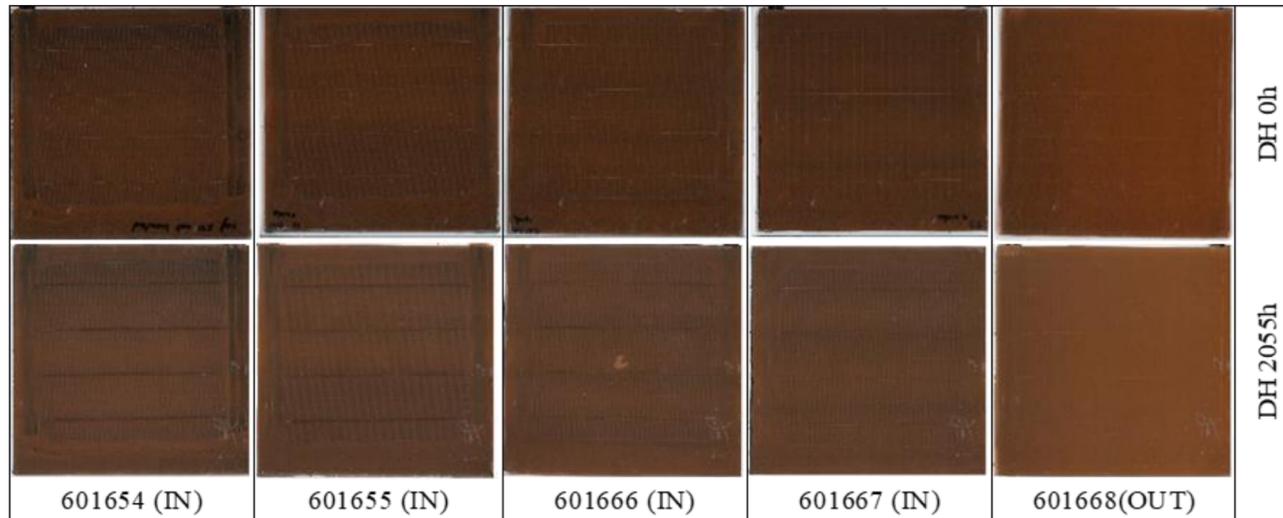
- Temp. 70°C
- Irr. 0.8 W/m<sup>2</sup> @ 340 nm
- Time: 4000h





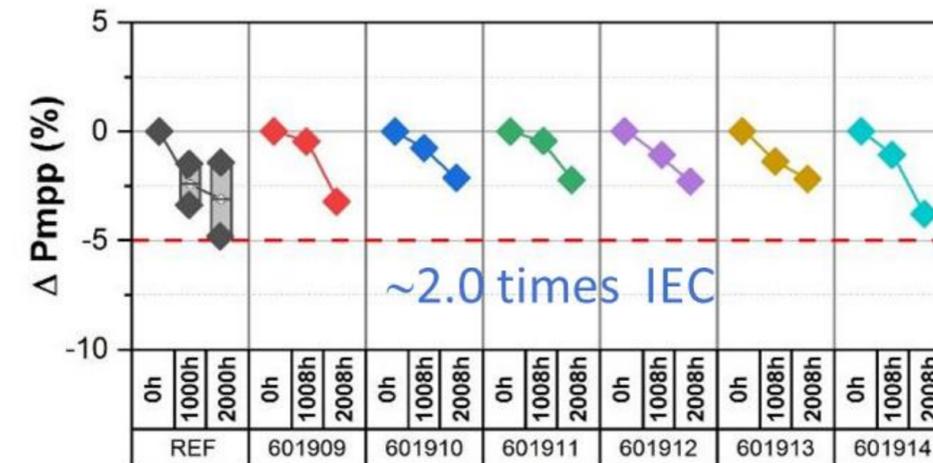
# Extended reliability testing

- Mini-modules with coloured low temperature encapsulant



### IEC DH test

- Temp 85°C
- Humidity: 85%
- Time: 1000h





**Thank you  
for your attention.**